

Abstract of the Disclosure

A radiation sensitive resin composition which is sensitive to various types of radiation and excellent in terms of resolution and pattern shape, has small film surface roughness and optical proximity effect, and is useful as a chemically amplifying positive resist capable of forming a fine line-and-space pattern, fine isolated pattern and fine contact hole pattern with high accuracy and stability.

The radiation sensitive resin composition comprises a polymer containing p-hydroxystyrene and p-cyclohexyloxymethyloxystyrene as polymer units, a polymer containing p-hydroxystyrene and p-t-butoxycarbonyloxystyrene as polymer units, and a radiation sensitive acid-generating agent.

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